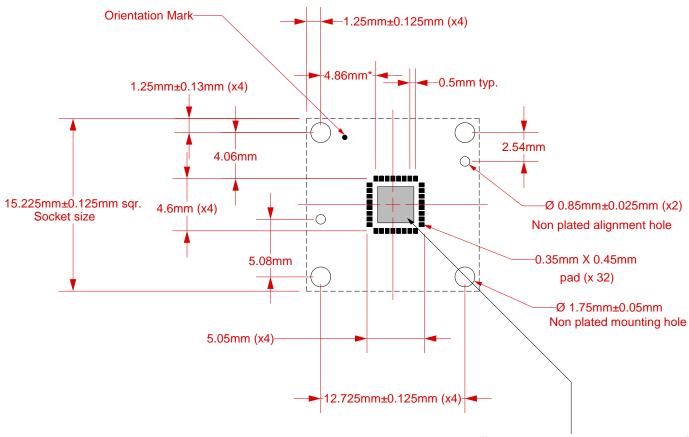


SG-MLF-7023 Drawing	Status: Released	Scale:	: -	Rev: D
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 5/15/07	
	File: SG-MLF-7023 Dwg.mcd		Modified: 11/11/14	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

\*Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.



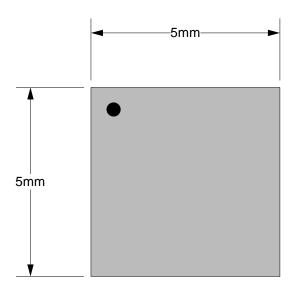
Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish

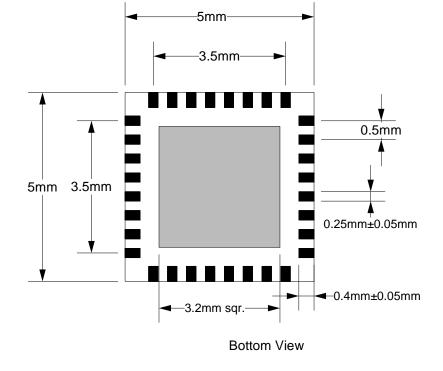
PCB Pad height: Same or higher than solder mask

\*\*\*\* To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

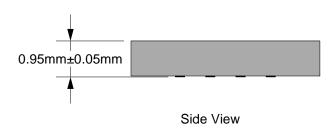
## NOTE: Steel backing plate may be required based on end user's application

SG-MLF-7023 Drawing	Status: Released	Scale:	-	Rev: D
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 5/15/07	
	File: SG-MLF-7023 Dwg.mcd		Modified: 11/11/14	









SG-MLF-7023 Drawing	Status: Released	Scale:	-	Rev: D
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 5/15/07	
	File: SG-MLF-7023 Dwg.mcd		Modified: 11/11/14	